

GANE1R8-100QBA

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

13 March 2025

Product data sheet

1. General description

The GANE1R8-100QBA is a general purpose 100 V, 1.8 m Ω Gallium Nitride (GaN) FET in a Very-Thin-Profile Quad Flat No-Lead Package (VQFN) package. It is a normally-off e-mode device offering superior performance and very low on-state resistance.

2. Features and benefits

- Enhancement mode - normally-off power switch
- Ultra high frequency switching capability
- No body diode
- Low gate charge, low output charge
- Qualified for standard applications
- RoHS, Pb-free, REACH-compliant
- High efficiency and high power density
- Very-Thin-Profile Quad Flat No-Lead Package (VQFN) 4.0 mm x 6.0 mm

3. Applications

- High power density and high efficiency power conversion
- AC-to-DC converters, (secondary stage)
- High frequency DC-to-DC converters in 48 V systems
- Fast battery charging, mobile phone, laptop, tablet and USB type-C chargers
- Datacom and telecom (AC-to-DC and DC-to-DC) converters
- Motor drives
- LiDAR (non-automotive)
- Class D audio amplifiers

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$-40\text{ }^{\circ}\text{C} \leq T_j \leq 150\text{ }^{\circ}\text{C}$	-	-	100	V
I_D	drain current	$V_{GS} = 5\text{ V}; T_{mb} = 25\text{ }^{\circ}\text{C}$	[1]	-	100	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ }^{\circ}\text{C}$; Fig. 1	-	-	65	W
T_j	junction temperature		-40	-	150	$^{\circ}\text{C}$
Static characteristics						
R_{DSon}	drain-source on-state resistance	$V_{GS} = 5\text{ V}; I_D = 40\text{ A}; T_j = 25\text{ }^{\circ}\text{C}$; Fig. 8 ; Fig. 9 ; Fig. 10	-	1.4	1.8	m Ω
		$V_{GS} = 5\text{ V}; I_D = 40\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$; Fig. 8 ; Fig. 11	-	2.8	-	m Ω
R_G	gate resistance	$f = 5\text{ MHz}$; open drain	-	1.8	-	Ω

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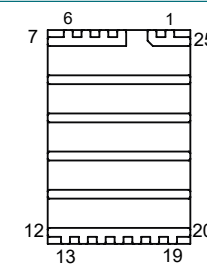
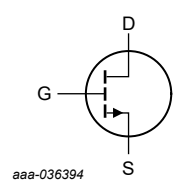
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Dynamic characteristics						
Q_{GD}	gate-drain charge	$I_D = 40\text{ A}$; $V_{DS} = 50\text{ V}$; $V_{GS} = 5\text{ V}$; $T_j = 25\text{ °C}$; Fig. 12 ; Fig. 13	-	4.5	-	nC
$Q_{G(\text{tot})}$	total gate charge	$T_j = 25\text{ °C}$; Fig. 12 ; Fig. 13	-	22	-	nC
Q_{oss}	output charge	$V_{GS} = 0\text{ V}$; $V_{DS} = 50\text{ V}$; Fig. 16	[2]	125	-	nC

[1] Limited by package

[2] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and $Q_D = 0$. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1,2,25	G	gate	 <p>Transparent top view VQFN7 (SOT8091-1)</p>	 <p>aaa-036394</p>
12-20	D	drain		
21,23	S	source		
22,24	D	drain		
3-7	S	source		
8,10	D	drain		
9,11	S	source		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
GANE1R8-100QBA	VQFN7	very thin quad flatpack; no leads	SOT8091-1

7. Marking

Table 4. Marking codes

Type number	Marking code
GANE1R8-100QBA	1R8DQBA

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$-40\text{ °C} \leq T_j \leq 150\text{ °C}$	-	100	V
V_{GS}	gate-source voltage		-4	6	V
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; Fig. 1	-	65	W
I_D	drain current	$V_{GS} = 5\text{ V}$; $T_{mb} = 25\text{ °C}$	[1]	100	A
I_{DM}	peak drain current	pulsed; $t_p = 100\text{ }\mu\text{s}$; $T_{mb} = 25\text{ °C}$; Fig. 2	-	320	A

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Symbol	Parameter	Conditions	Min	Max	Unit
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-40	150	°C
T _{sld(M)}	peak soldering temperature		-	260	°C

[1] Limited by package

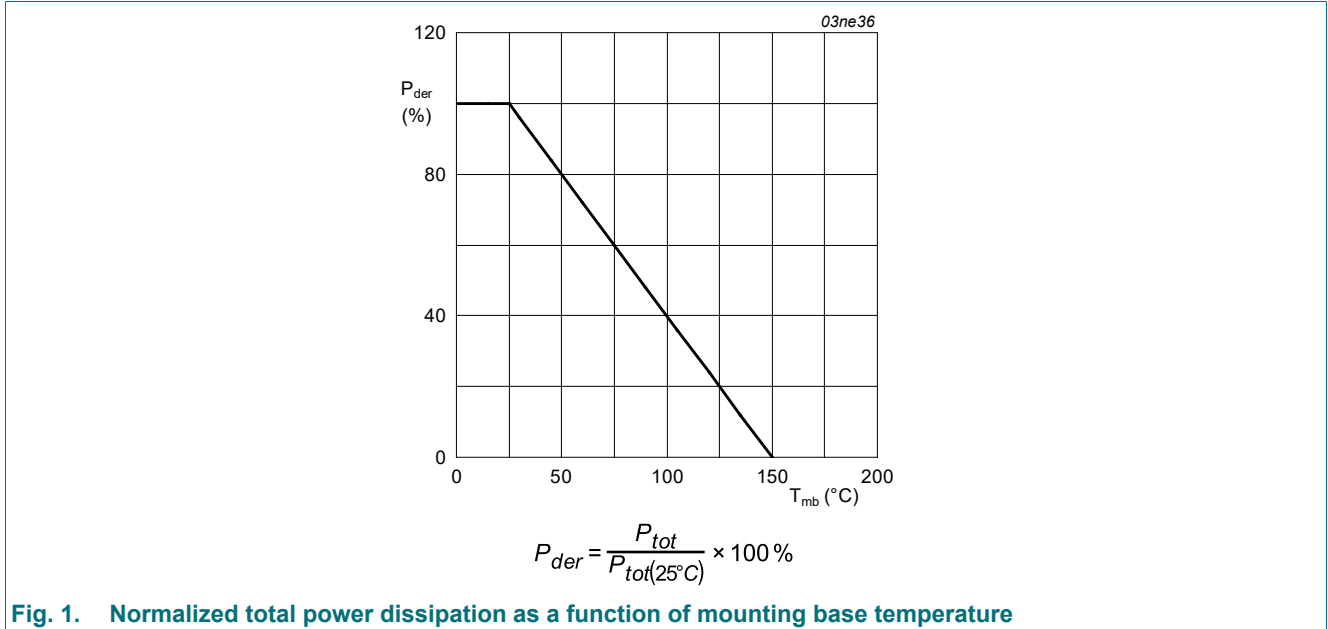


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

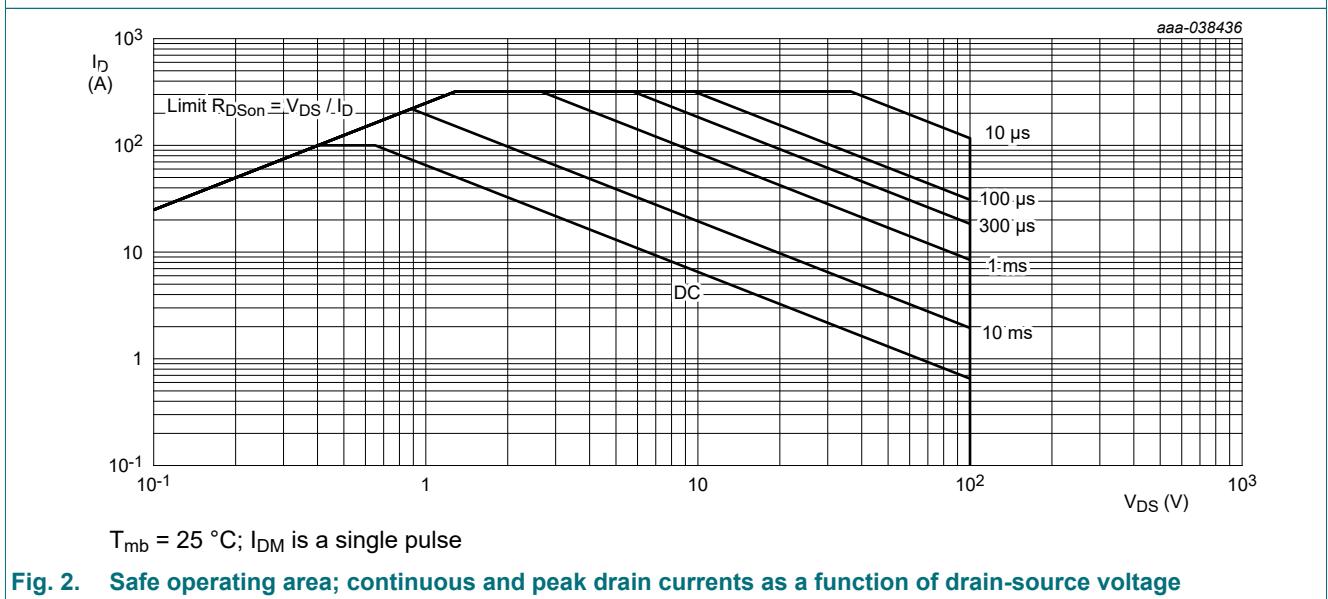


Fig. 2. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R _{th(j-c)}	thermal resistance from junction to case		-	-	13.96	K/W

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Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 3	-	-	1.92	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	[1]	-	-	57.56	K/W

[1] $R_{th(j-a)}$ is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board.

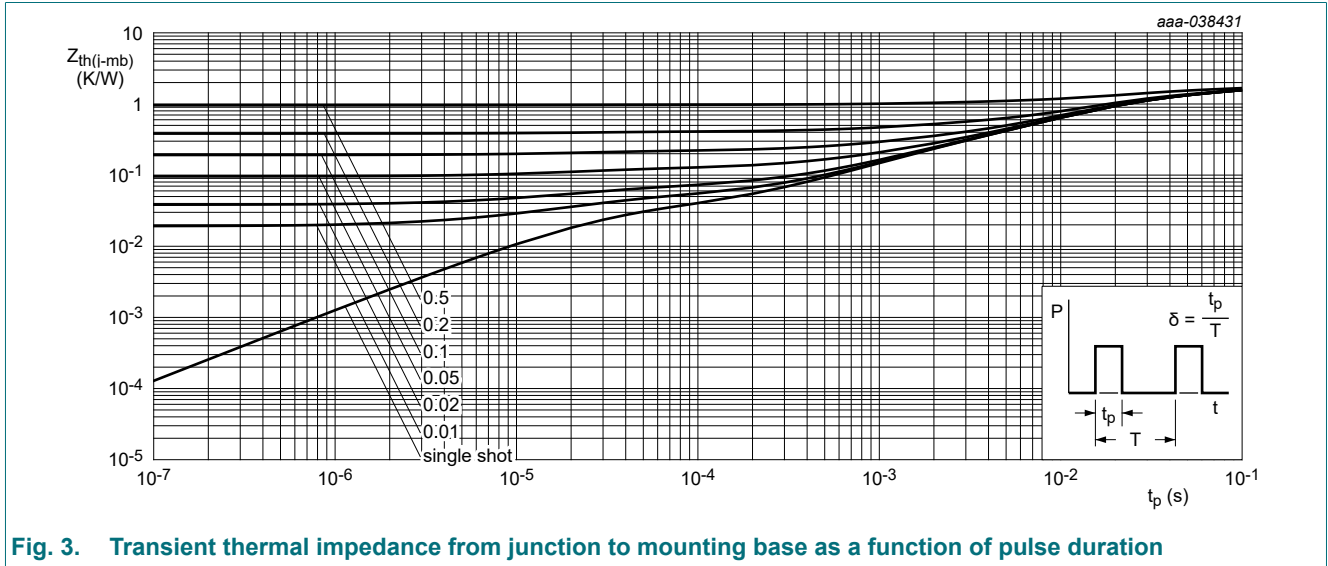


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

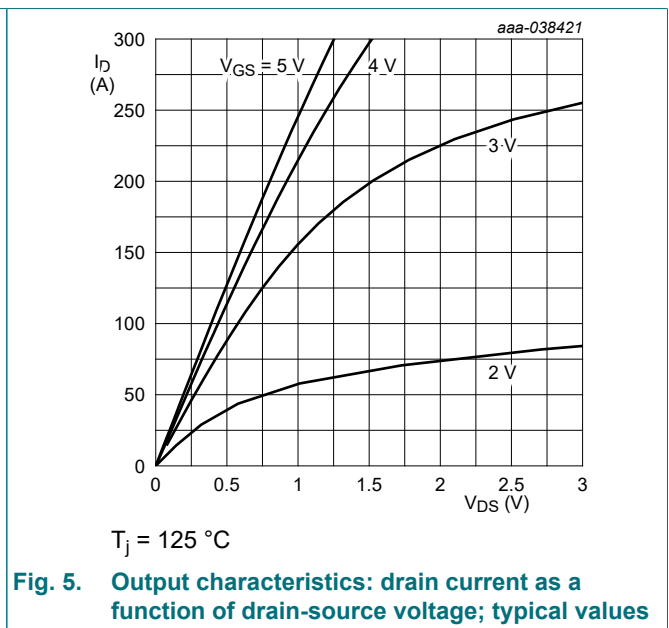
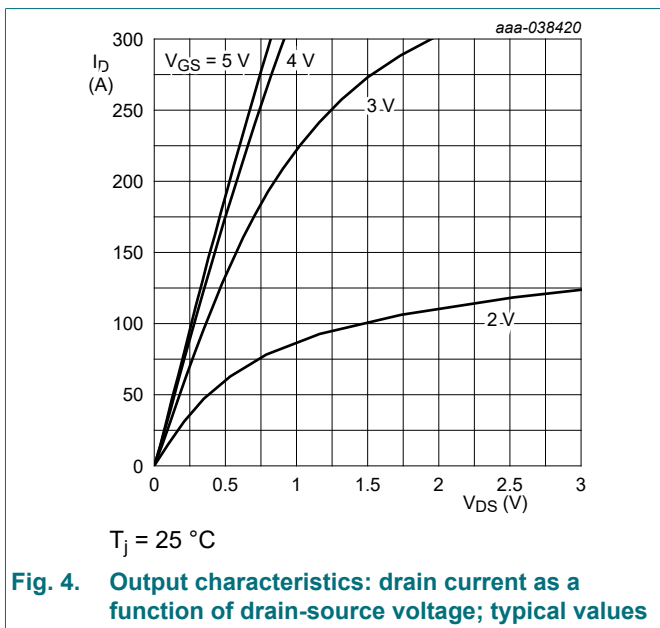
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 21 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C};$ Fig. 7	0.8	1.1	2.5	V
		$I_D = 21 \text{ mA}; V_{DS} = V_{GS}; T_j = 150 \text{ }^\circ\text{C};$ Fig. 7	-	1	-	V
I_{DSS}	drain leakage current	$V_{DS} = 80 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	9.5	93	μA
I_{GSS}	gate leakage current	$V_{GS} = 5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2.8	55	μA
		$V_{GS} = 5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 125 \text{ }^\circ\text{C}$	-	136	2700	μA
		$V_{GS} = -4 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	0.3	1.2	μA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 5 \text{ V}; I_D = 40 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$ Fig. 8; Fig. 9; Fig. 10	-	1.4	1.8	m Ω
		$V_{GS} = 5 \text{ V}; I_D = 40 \text{ A}; T_j = 150 \text{ }^\circ\text{C};$ Fig. 8; Fig. 11	-	2.8	-	m Ω
R_G	gate resistance	$f = 5 \text{ MHz};$ open drain	-	1.8	-	Ω
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 40 \text{ A}; V_{DS} = 50 \text{ V}; V_{GS} = 5 \text{ V}; T_j = 25 \text{ }^\circ\text{C};$ Fig. 12; Fig. 13	-	22	-	nC
Q_{GS}	gate-source charge		-	4.5	-	nC
Q_{GD}	gate-drain charge		-	4.5	-	nC

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C_{iss}	input capacitance	$V_{DS} = 50\text{ V}; V_{GS} = 0\text{ V}; f = 100\text{ kHz}; T_j = 25\text{ }^\circ\text{C};$ Fig. 14	-	2500	-	pF
C_{oss}	output capacitance		-	1100	-	pF
C_{rss}	reverse transfer capacitance		-	19	-	pF
$C_{o(er)}$	effective output capacitance, energy related	$V_{DS} = 50\text{ V}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C};$ Fig. 15	[1]	1700	-	pF
$C_{o(tr)}$	effective output capacitance, time related	$V_{DS} = 50\text{ V}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$	[2]	2500	-	pF
Q_{oss}	output charge	$V_{GS} = 0\text{ V}; V_{DS} = 50\text{ V};$ Fig. 16	[3]	125	-	nC
Source-drain characteristics						
V_{SD}	source-drain voltage	$I_S = 0.5\text{ A}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C};$ Fig. 17 ; Fig. 18 ; Fig. 19 ; Fig. 20	-	1.5	-	V

- [1] $C_{o(er)}$ is the fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 50 V
- [2] $C_{o(tr)}$ is the fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 50 V
- [3] Q_r is not specified separately from Q_{oss} for e-mode GaN FETs, since $Q_r = Q_{oss} + Q_D$, and $Q_D = 0$. (Q_D is charge associated with diffusion of minority carriers. Since there is no body diode, no minority carriers in excess of Q_{oss} have to be transferred for e-mode GaN FETs.)



100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

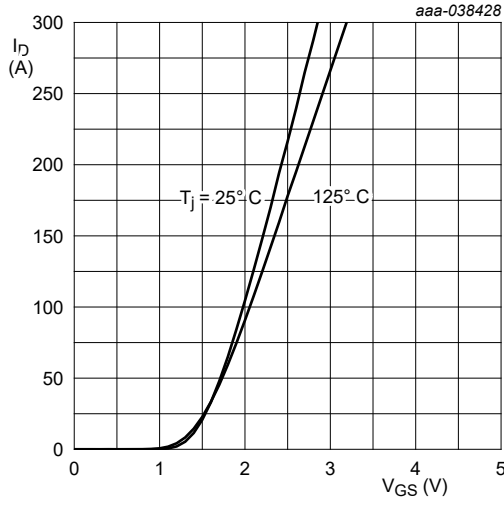


Fig. 6. Transfer characteristics; drain current as a function of gate-source voltage; typical values

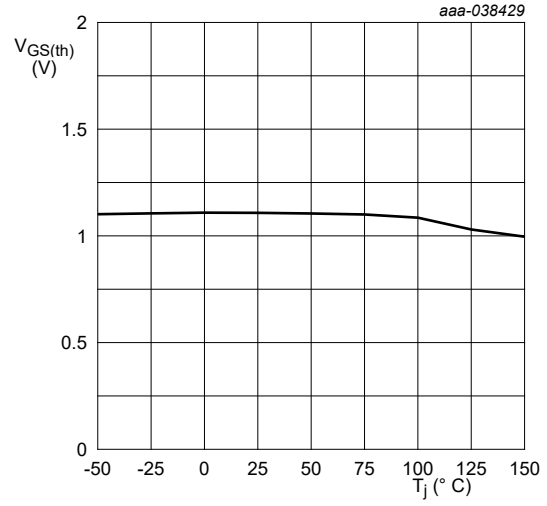
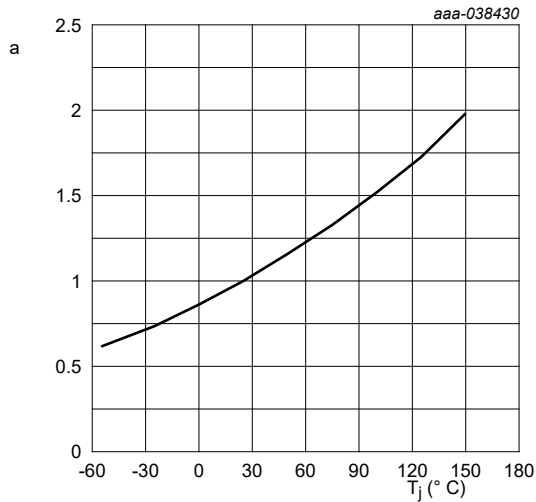


Fig. 7. Gate-source threshold voltage as a function of junction temperature; typical values



$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig. 8. Normalized drain-source on-state resistance factor as a function of junction temperature

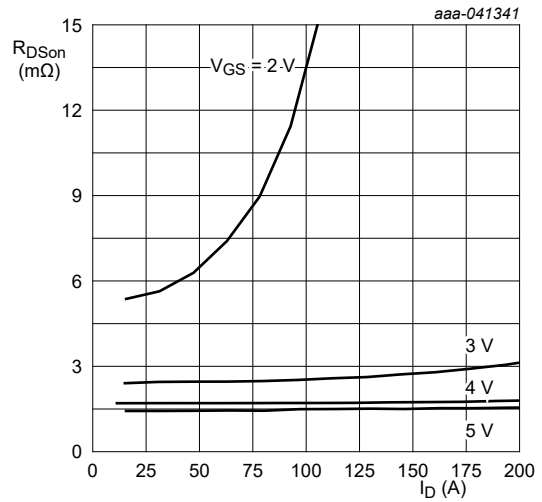


Fig. 9. Drain-source on-state resistance as a function of drain current ; typical values

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

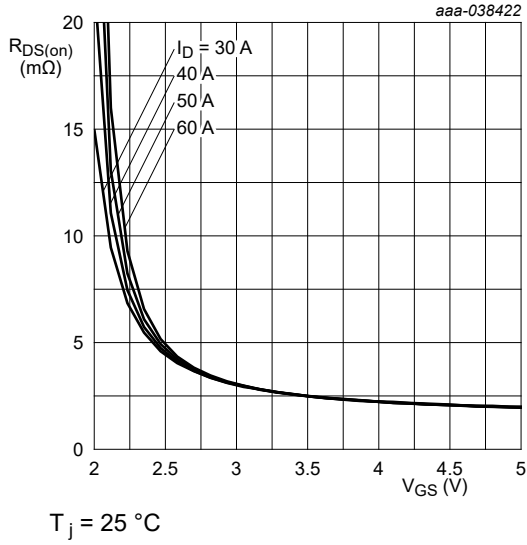


Fig. 10. Drain-source on-state resistance as a function of gate-source voltage; typical values

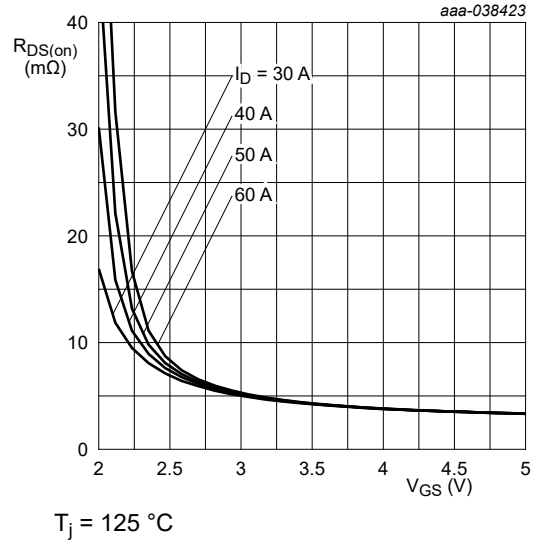


Fig. 11. Drain-source on-state resistance as a function of gate-source voltage; typical values

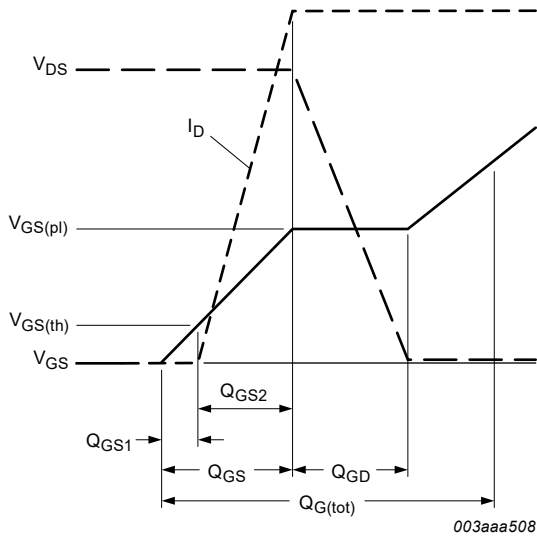


Fig. 12. Gate charge waveform definitions

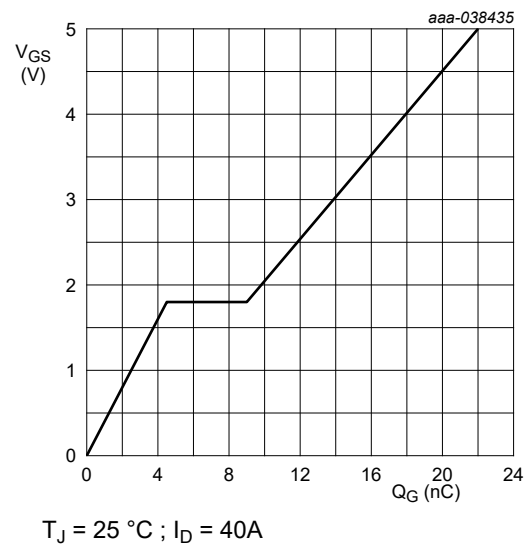
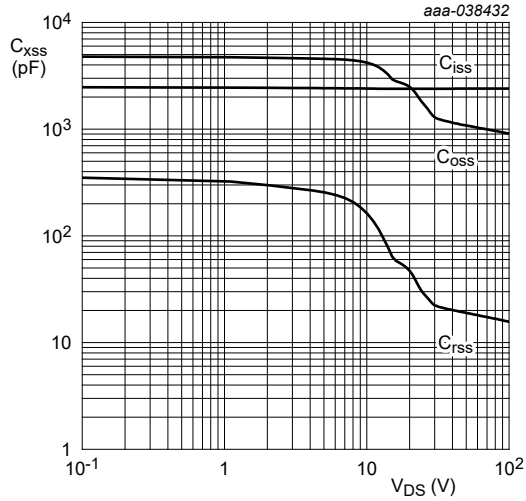


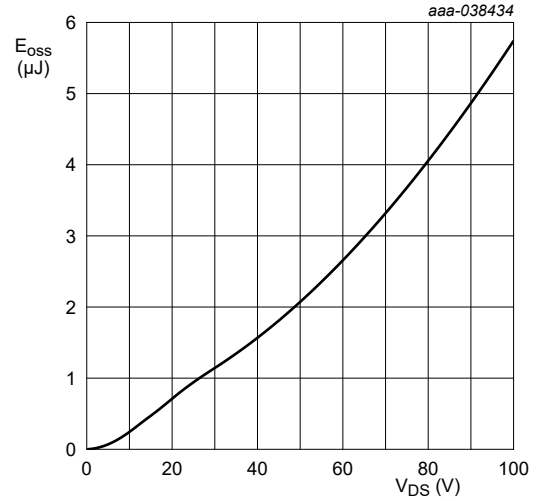
Fig. 13. Gate-source voltage as a function of gate charge; typical values

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)



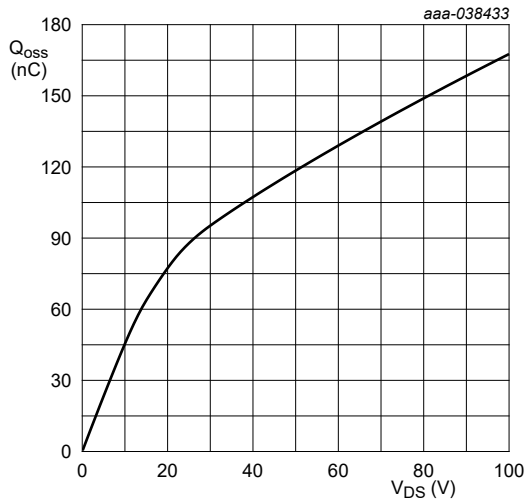
$V_{GS} = 0\text{ V}$; $f = 100\text{ kHz}$

Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



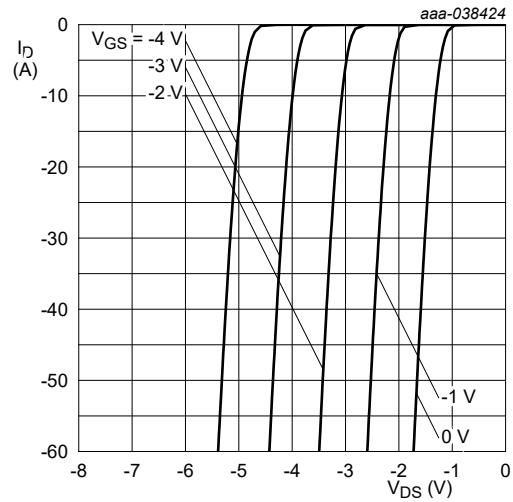
Freq. = 100 kHz

Fig. 15. COSS stored energy as a function of drain-source voltage; typical values



Freq. = 100 kHz

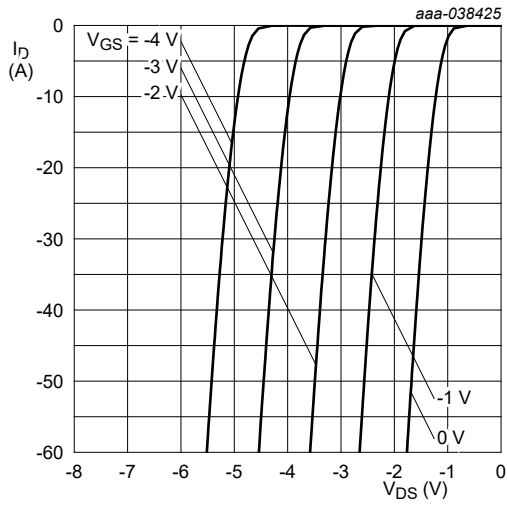
Fig. 16. Output charge as a function of drain-source voltage; typical values



$T_j = 25\text{ }^\circ\text{C}$

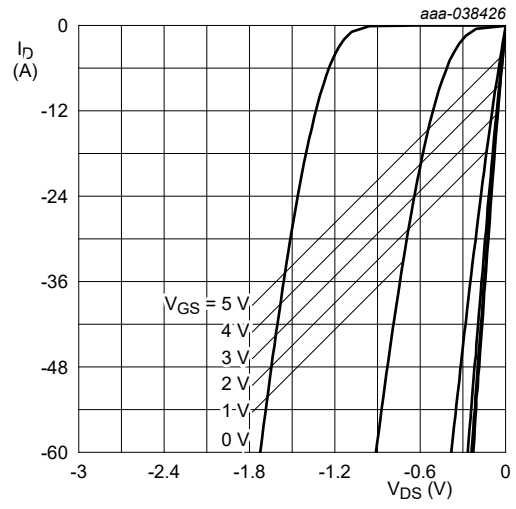
Fig. 17. Source current as a function of source-drain voltage; typical values

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)



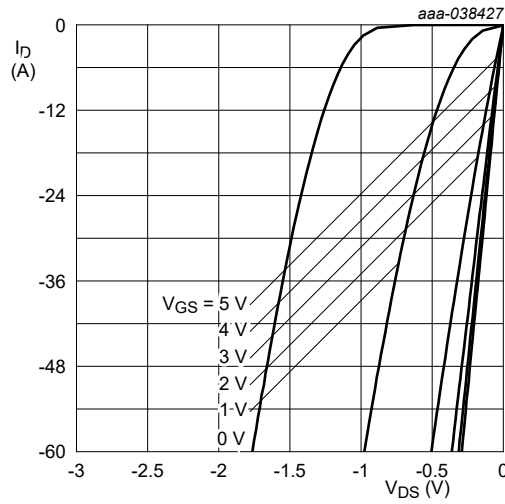
$T_j = 125\text{ °C}$

Fig. 18. Source current as a function of source-drain voltage; typical values



$T_j = 25\text{ °C}$

Fig. 19. Source current as a function of source-drain voltage; typical values



$T_j = 125\text{ °C}$

Fig. 20. Source current as a function of source-drain voltage; typical values

11. Package outline

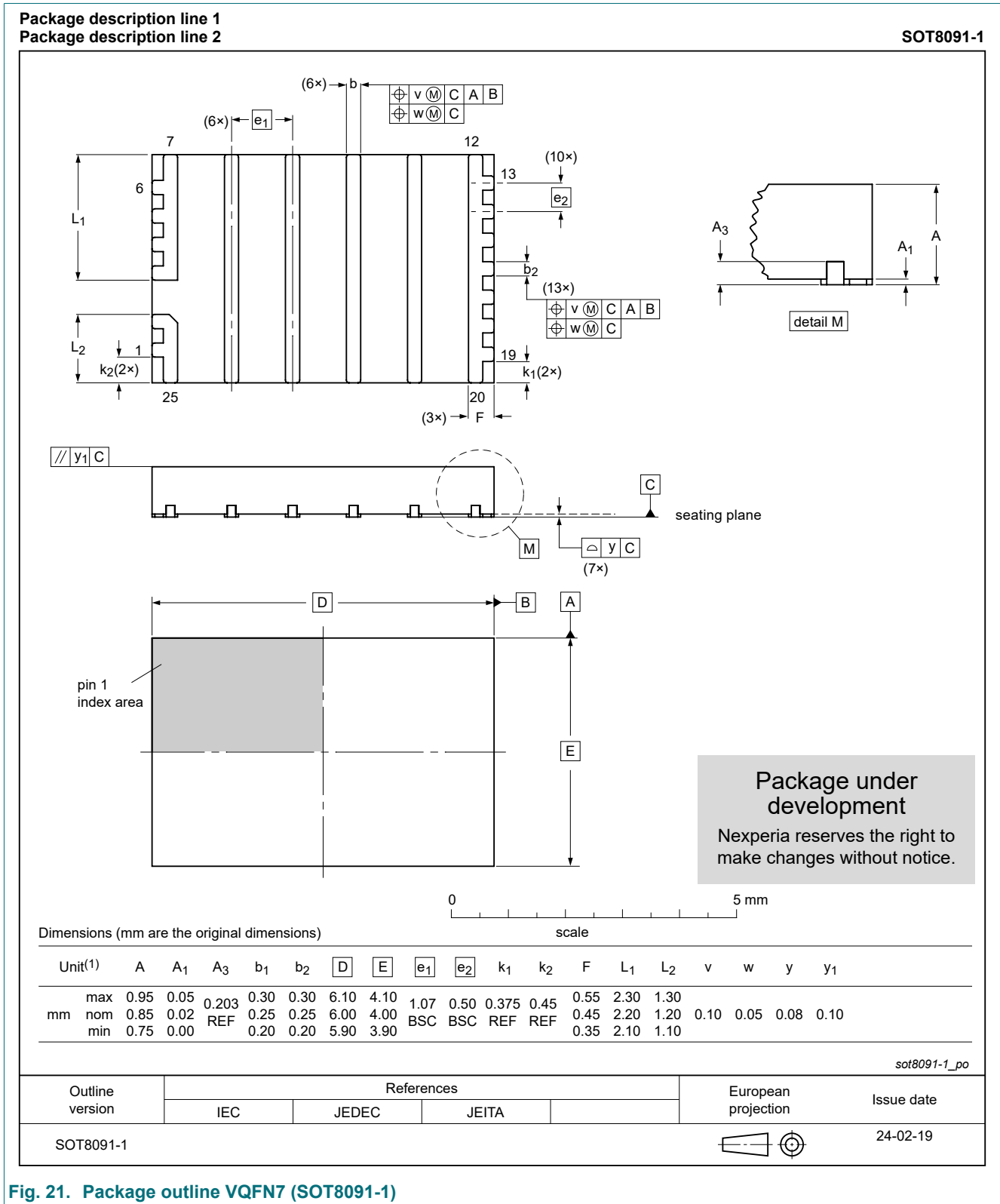


Fig. 21. Package outline VQFN7 (SOT8091-1)

12. Soldering

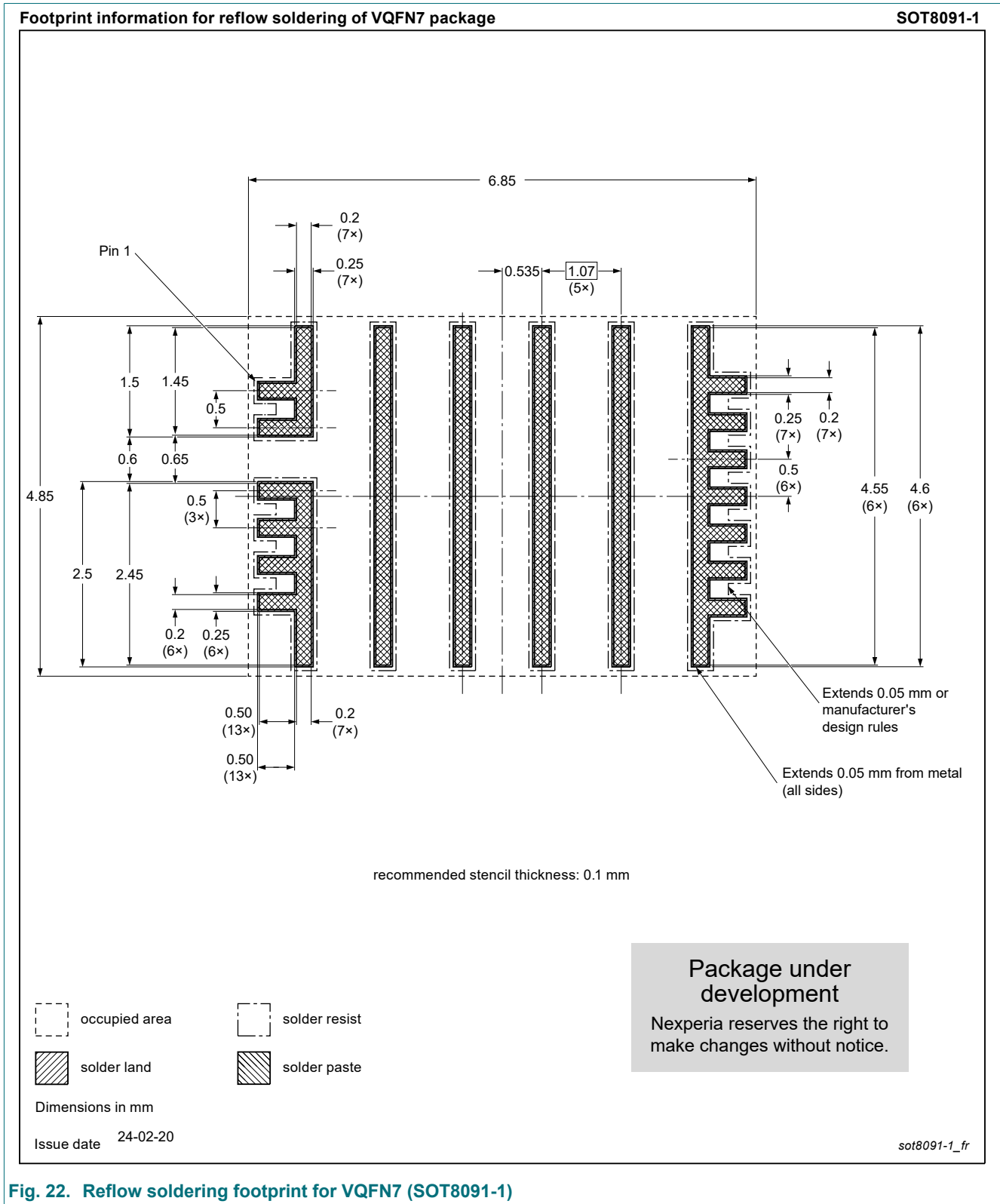


Fig. 22. Reflow soldering footprint for VQFN7 (SOT8091-1)

100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

13. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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100 V, 1.8 mOhm Gallium Nitride (GaN) FET in a 4.0 mm x 6.0 mm Very-Thin-Profile Quad Flat No-Lead Package (VQFN)

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